



DirectFET Medium Can

RoHS Compliance Document

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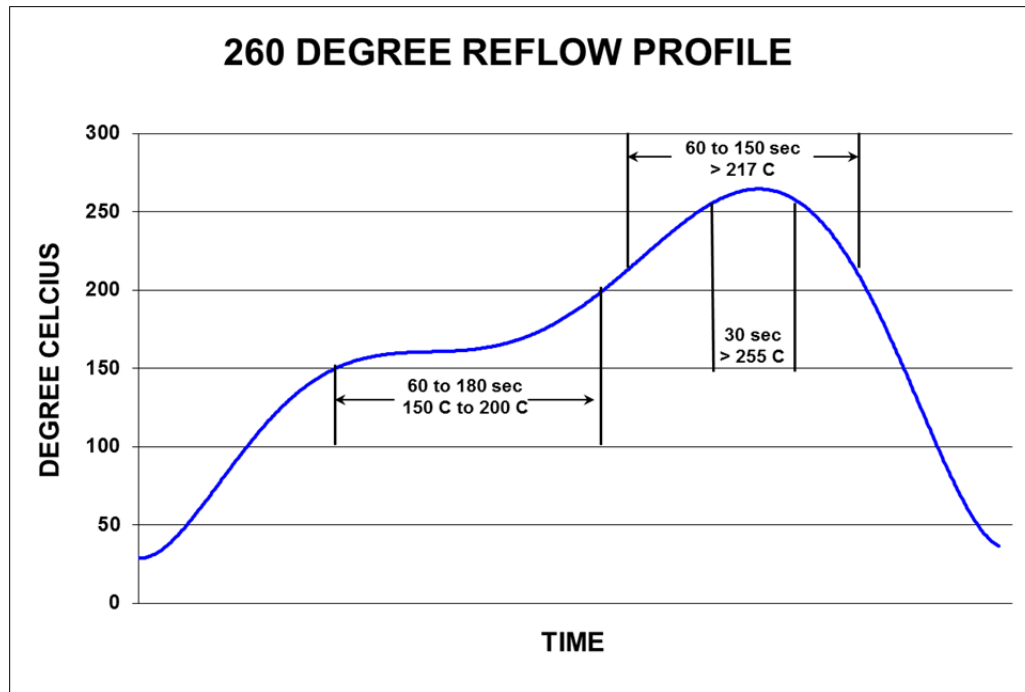
DirectFET - Medium Can

Component	Material Name	Material Mass (g)	Element Name Composition	CAS #	Substance Mass (g)	Material Analysis Weight (%)	% of Total Weight
Chip	Silicon	0.00721	Si	7440-21-3	0.00687	95%	7.9%
			Epoxy	90598-46-2	0.00034	5%	0.4%
Lead Frame	Plated Copper	0.07662	Cu	7440-50-8	0.07432	97%	85.4%
			Ni	7440-02-0	0.00077	1%	0.9%
			Ag	7440-22-4	0.00153	2%	1.8%
Die Attach	Silver Epoxy	0.00187	Ag	7440-22-4	0.00139	75%	1.6%
			Epoxy	90598-46-2	0.00048	25%	0.5%
Solder	Solder Bumps	0.00135	Sn	7440-31-5	0.00126	93%	1.4%
			Ag	7440-22-4	0.00008	6%	0.1%
			Cu	7440-50-8	0.00001	1%	0.0%

Total Weight
(g)

0.08705

No tin whisker mitigation strategy



This part is compliant with EU Directive 2011/65/EU (RoHS Directive) and does not contain lead, mercury, cadmium (0.01%), hexavalent chromium, PBB or PBDE in concentrations greater than 0.1%, except as permitted by Annex III. Further part complies with 3 reflow cycles per JEDEC J-STD-020